

ABSTRACT

The purpose is to provide a surface treated copper foil and an electrodeposited copper foil with carrier to be employed for a copper clad laminate capable to be processed for simultaneous hole formation in the copper foil layer and a substrate resin layer using carbon dioxide gas laser. The purpose can be achieved by using a surface treated copper foil bearing a nickel layer or a cobalt layer with a prescribed thickness in one side of a copper foil or an electrodeposited copper foil with carrier provided with a nickel layer or a cobalt layer with a prescribed thickness between a carrier foil and an electrodeposited copper foil layer. When a copper clad laminate is manufactured using these foils, the copper clad laminate is capable to be processed to easily and simultaneously form a hole in the copper foil layer and the substrate resin layer using carbon dioxide gas laser.